



PCIe x4 Host to CPCle Kit Server to CPCle backplane

PCIe expansion kit with upstream PCIe x4 switch-based host cable adapter, downstream 3U CPCle expansion link board, and PCIe x4 2M cable.

PN: OSS-KIT-EXP-6002

Features

- The host adapter card inserts into any PCI Express x4 slot on the host motherboard.
- The high speed PCIe cable allows data transfers to and from the host up to 20Gb/s.
- The 3U CPCle target expansion link board installs in a system slot of CPCle backplane to provide operation of the downstream I/O boards.
- Software transparent, no drivers required.



Specifications

PCIe x4 Switch-Based Host Cable Adapter	
Form Factor:	PCIe half-card
Operating Temperature:	0°C to +50°C environment
Storage Temperature:	-40°C to 85°C
Operating Humidity:	10% to 90% relative humidity non-condensing
Storage Humidity:	5% to 95% relative humidity non-condensing
Power:	4W
Connectors:	PCIe x4 cable connector PCIe x4 edge connector
Industry Specifications:	PCIe External Cabling Specification, Rev. 1.0 PCI Express™ Card Electromechanical Specification, Rev. 2.0 PCI Express® Base Specification, Rev. 2.0 ATX Specification, Version 2.2
Switch:	PEX8609 Gen 2 (5.0 GT/s) 8 lane PCIe Switch
Bracket:	HIB35 x4 add-in card bracket Standard and low profile brackets available Link Status LEDs
Agency Compliance:	FCC Class A CE RoHS



Specifications subject to change without notice



CPCle x4 Expansion Link Board	
Form Factor:	PICMG EXP. 0 system slot compliant. Single slot.
Dimensions:	(H x L) 3.937 x 6.299 in (100 x 161 mm), 1 slot wide
Switch:	PLX PEX8733 32 lane enhanced switch including <ul style="list-style-type: none"> • Configurable lane configuration based on PXle or CPCle backplane • Spread spectrum clock isolation • DMA controller
External Interface:	One x4 PCIe cable input <ul style="list-style-type: none"> • PCI-SIG PCI Express Cable Rev 2.0 compliant
Downstream Interface:	16 lanes of PCI Express on the backplane connectors. The lanes form two or four links to the backplane through the XP2 and XP3 connectors per the PICMG EXP.0 specification. The following link modes are automatically selected by the backplane as follows: <ul style="list-style-type: none"> • Two link mode: 2 x8 links (per backplane capabilities) • Four link mode: Four x4 PCIe links
Front Panel Connector:	Molex 75586-0010
Front Panel Indicators:	4 backplane link-active indicators (green) 2 or 4 link mode + cable link (green)
Power Consumption:	10W typical +12V @ .5, 3.3V @ 1.25A, 5Vaux @ 2.5mA
Temperature Range:	0° to 50°C
Relative Humidity:	10 to 90% non-condensing
Agency/Compliances:	Designed to Meet: FCC Class A CE RoHS